Docket No.

215207US0PCT

IN RE APPLICATION OF: Hiroshi ORIKABE, et al.

SERIAL NO: 09/926,370

FILED:

December 28, 2001

FOR:

THERMOSETTING RESIN COMPOSITION AND FLEXIBLE CIRCUIT OVERCOATING MATERIAL

COMPRISING THE SAME

COMMISSIONER FOR PATENTS ALEXANDRIA, VIRGINIA 22313

STR

Transmitted herewith is an amendment in the above-identified application.

- No additional fee is required
- ☐ Small entity status of this application under 37 C.F.R. §1.9 and §1.27 is claimed.
- ☐ Additional documents filed herewith:

The Fee has been calculated as shown below:

| CLAIMS | CLAIMS REMAINING | | HIGHEST NUMBER PREVIOUSLY PAID | NO. EXTRA CLAIMS | | RATE | | CALCULATIONS |
|-------------|---------------------|---|---|------------------------|---|--------|--------|--------------|
| TOTAL | 16 | MINUS | 20 | 0 | х | \$18 | = | \$0.00 |
| INDEPENDENT | 1 | MINUS | 3 | 0 | х | \$84 | = | \$0.00 |
| | | ☐ MULTIPI | E DEPENDENT | CLAIMS | + | \$280 | = . | \$0.00 |
| | | TOTAL OF ABOVE CALCULATIONS | | | | | \$0.00 | |
| | | ☐ Reduction by 50% for filing by Small Entity | | | | \$0.00 | | |
| : | | ☐ Recordation of Assignment + | | | + | \$40 | = | \$0.00 |
| | | | -0 | | | TOT | AL | \$0.00 |

| \Box | Α | check | in t | the amount | Λ \$ Ω (| nn ic | attached |
|--------|---|-------|------|------------|-----------------|-------|----------|
| | | | | | | | |

- Please charge any additional Fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.
- If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136, and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

OBLON, SPIVAK, McCLELLAND, MAIER & NEWSTADT, PAC.

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Registration No.

24,618

DOCKET NO.: 215207US0PCT

GROUP 1700

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

XE APPLICATION OF

HIROSHI ORIKABE, ET AL. : ATTN: APPLICATION DIVISION

SERIAL NO: 09/926,370

FILED: DECEMBER 28, 2001 : GROUP ART UNIT: 1755

FOR: THERMOSETTING RESIN

COMPOSITION AND FLEXIBLE

CIRCUIT OVERCOATING

MATERIAL COMPRISING THE

SAME

PRELIMINARY AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

SIR:

Prior to examination on the merits, please amend the above-identified application as follows: